



Product Content Sheet

Package family	QFN	
Date	2005-02-28	
Version	RoHS	

Composition part	Material group	Materials	CAS if applicable	Average mass [weight-% *)	Sum [%]	Traces	
Chip	Silicon and inorganic compounds	Silicon	7440-21-3	100	4.63		
Wires	Nobel Metal	Gold	7440-57-5	99.99	0.50		
Leadframe	Alloy	Cu	7440-50-8	97.50	42.12		
		Fe	7439-89-6	2.35	0.995		
		P	7723-14-0	0.03	0.012		
		Zn	7440-66-6	0.12	0.050		
Diepad	Aluminised Die		N/A	N/A	N/A		
Mold compound	Silica	SiO2	60676-86-0	89	45.18		
		Epoxy resin	Biphenyl	Confidential	10.8	5.49	
			Carbon Black	1333-86-4	0.2	0.10	
DA Epoxy	Epoxy	Epoxy resin	Confidential	23	0.147		
			Silver	7440-02-24	77	0.492	
Leadfinish	Metal Alloy	Tin	7440-31-5	100	0.3		
Marking	Laser			0	0		
Sum in total:					100		

Weight range	0.13 gram
Fluctuation margin	+/-25%

or:

Case sizes**) and weight range

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*) related to package weight; weight in particular, see corresponding *package weight list*

**) optional

Not part of package family	
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Company	Chipcon	Important remarks: 1) Traces are product parts, substances etc. that are below a percentage of 0.1 % by weight. Higher limits are accepted if the substance or material is legally regulated (see note no. 2). 2) A list of the (legal) "... restrictions on substances ..." or materials is available at internet address: http://www.eicta.org/Content/Default.asp?PageID=113 . 3) Substances, materials etc. with possible harmful effects on
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- 4) human beings and the environment are listed.
 There are no risks for human beings and to the environment if products are properly used as designated.
 This shall not apply to risks caused during procedures for disposal etc.
- 5) All statements herein are based on our present knowledge.
 If our products are used properly, there are no risks to human beings and/or the environment.



Package Weight List

(Single weights of Products, materials data see Product Content Sheet on previous page)

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Version	

Uspec short*)	Package family*)	Package	Internal package code	Pin count	Weight [grams]	Remark
10273-022	QFN	QFN32	QFN32	32	0.13 g	Device: CC1021

*) USpec short name and Package family are optional, e.g. for summary of several package weight lists

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